

Capacitor Arrays

■ HOW TO ORDER

Υ	4C	3	В	103	K	500	С	Т
<u>Series</u>	Cap. Nr.	Termination pitch	<u>Dielectric</u>	<u>Capacitance</u>	<u>Tolerance</u>	Rated voltage	<u>Termination</u>	<u>Packaging</u>
Y=Capacitor Array	4C=4xCap	3=0.03" pitch	N=NPO (COG) B=X7R F=Y5V	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: 103=10x10³ =10,000pF =10nF	J=±5% K=±10% M=±20% Z=+20/-80%	Two significant digits followed by no. of zeros. And R is in place of decimal point. 160=16 VDC 250=25 VDC 500=50 VDC	L=Ag/Ni/Sn (for NP0 dielectric) C=Cu/Ni/Sn (for X7R, Y5V dielectric)	T=7" reeled

■ PACKAGING DIMENSION AND QUANTITY

C:	This large (com) (Complete)		Paper tape		
Size	Thickness (mm)/Symbol		7" reel	13" reel	
4 x 0603	0.80±0.10	В	4k	-	

Unit: pieces

■ CAPACITANCE RANGE

Size			4 x 0603				
	Dielectric	NP0	X7R		Y5V		
Rat	ed Voltage (VDC)	50	16	50	50		
	10pF (100)	В					
	15pF (150)	В					
	22pF (220)	В					
	33pF (330)	В					
	47pF (470)	В					
	68pF (680)	В					
	100pF (101)	В					
	150pF (151)	В					
	180pF (181)	В		В			
	220pF (221)	В		В			
	330pF (331)	В		В			
8	470pF (471)	В		В			
Capacitance	680pF (681)			В			
Saci	1,000pF (102)			В			
<u>a</u>	1,500pF (152)			В			
	2,200pF (222)			В			
	3,300pF (332)			В			
	4,700pF (472)			В			
	6,800pF (682)			В			
	0.010µF (103)			В	В		
	0.015µF (153)		В				
	0.022µF (223)		В		В		
	0.033µF (333)		В				
	0.047µF (473)		В		В		
	0.068µF (683)		В				
	0.10µF (104)		В		В		

^{1.} The letter in cell is expressed the symbol of product thickness.

^{2.} For more information about products with special capacitance or other data, please contact WTC local representative.



Appendix I: Reliability Test Conditions and Requirements

NO.	Item	Test Condition	Requirements			
1.	Visual and Mechanical		* No remarkable defect. * Dimensions to confirm to individual specification sheet.			
2.	Capacitance	Class I : NPO	* Shall not exceed the limits given in the detailed spec.			
3.	Q/ D.F. (Dissipation Factor)	Cap 1000pF 1.0±0.2Vrms, 1MHz±10% Cap>1000pF 1.0±0.2Vrms, 1KHz±10%	NPO: Cap 30pF, Q 1000; Cap<30pF, Q 400+20C X7R, X5R:			
	(Dissipation Factor)	OLAND VED VED	Rated vol. D.F. Exception of D.F.			
		Class II : X7R, X5R, Y5V Cap 10µF, 1.0±0.2Vrms, 1KHz±10%	50V 2.5% 3.0% All 0201;0603 0.047μF;0805 0.18μF;			
		Cap>10μF, 0.5±0.2Vrms, 120Hz±20%	25V 3.5% 5.0% 0805 1µF, 1210 10µF			
			7.0% 0603 0.33µF;TT series & Cap 1µF			
			16V 3.5% 0805 0.68μF;1206 2.2μF			
			10% TT series & Cap 1μF 10V 5.0% 10.0% TT series & Cap 1μF:0805 10μF			
			6.3V 10.0% 15.0% 0805 22μF;1210 100μF			
			Y5V:			
			Rated vol. D.F. Exception of D.F. 50V 5.0%			
			35V 7.0%			
			7.0% 0603 0.1µF; 0805 0.33µF;			
			25V 5.0% 7.0% 1206 1μF; 1210 4.7μF 9.0% 0402 0.068μF			
			16V (C<1.0μF) 7.0% 9.0% 0402 0.068μF; 0603 0.68μF			
			16V (C 1.0μF) 9.0% 12.5% 0805 4.7μF;1206 10μF;1210 22μF			
			10V 12.5% 6.3V 20.0%			
			0.37 20.070			
4a.	Dielectric Strength	* To apply voltage (50V) 250%.	* No evidence of damage or flash over during test.			
		* Duration: 1 to 5 sec. * Charge & discharge current less than 50mA.				
		* To apply voltage :				
		100V 3 times V DC				
		200V ~ 300V 2 times V DC 500V ~ 999V 1.5 times V DC				
		1000V ~ 3000V 1.2 times V DC				
		* Cut-off, set at 10mA				
		* TEST= 15 sec. * RAMP=0				
4b.	Dielectric Strength (for X1/Y2 & X2/Y3)	* To apply 1500 VAC voltage. * Duration: 60 sec.	* No evidence of damage or flash over during test.			
5.	Insulation Resistance	To apply rated voltage for max. 120 sec.	10G or RxC 500 -F whichever is smaller.			
		Rated voltage: 100 ~ 500V To apply rated voltage for 60 sec.	10G			
		Rated voltage: To apply 500V for 60 sec.	10G			
		> 500V				
6.	Temperature	With no electrical load.				
	Coefficient	T.C. Operating Temp	T.C. Capacitance Change			
		NP0 (C0G) -55~125°C at 25°C NP0 (C0J) -55~125°C at 25°C	NP0 (COG) Within ±30ppm/°C NP0 (COJ) Within ±120ppm/°C			
		X7R -55~125°C at 25°C	X7R Within ±15%			
		X5R -55~85°C at 25°C	X5R Within ±15%			
		Y5V -25~85°C at 20°C	Y5V Within +30%/-80%			
7.	Adhesive Strength	* Pressurizing force:	* No remarkable damage or removal of the terminations.			
	of Termination	0201: 2N				
		0402 & 0603: 5N >0603: 10N				
		* Test time: 10±1 sec.				
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.			
	Resistance	* Total amplitude: 1.5mm	* Cap change and Q/D.F.: To meet initial spec.			
		* Test time: 6 hrs. (Two hrs each in three				
		mutually perpendicular directions.)				



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NO.	Item	Test Condition	Requirements		
9.	Solderability	* Solder temperature: 235±5°C * Dipping time: 2±0.5 sec.	95% min. coverage of all metalized area.		
10.	Bending Test	* The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec. * Measurement to be made after keeping at room temp. for 24±2 hrs.	* No remarkable damage. * Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R, X5R: within ±12.5% Y5V: within ±30% (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)		
11.	Resistance to Soldering Heat	* Solder temperature: 270±5°C * Dipping time: 10±1 sec * Preheating: 120 to 150°C for 1 minute before immerse the capacitor in an eutectic solder. * Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 48±4 hrs at room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).	* No remarkable damage. * Cap change: NPO: within ±2.5% or ±0.25pF whichever is larger. X7R, X5R: within ±7.5% Y5V: within ±20% * Q/D.F., I.R. and dielectric strength: To meet initial requirements. * 25% max. leaching on each edge.		
12.	Temperature Cycle	* Conduct the five cycles according to the temperatures and time. Step Temp. (°C) Time (min.) 1 Min. operating temp. +0/-3 30±3 2 Room temp. 2~3 3 Max. operating temp. +3/-0 30±3 4 Room temp. 2~3 * Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 48±4 hrs at room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).	* No remarkable damage. * Cap change: NPO: within ±2.5% or ±0.25pF whichever is larger. X7R, X5R: within ±7.5% Y5V: within ±20% * Q/D.F., I.R. and dielectric strength: To meet initial requirements.		
13.	Humidity (Steady State)	* Test temp.: 40±2°C * Humidity: 90~95% RH * Test time: 500+24/-0hrs. * Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).	* No remarkable damage. * Cap change: NPO: within ±5.0% or ±0.5pF whichever is larger. X7R, X5R: 10V, within ±12.5% 6.3V, within ±25% Y5V: within ±30% * Q/D.F. value: NPO: Cap 30pF, Q 350; 10pF Cap<30pF, Q 275+2.5C Cap<10pF; Q 200+10C X7R, X5R: Rated vol. D.E. Exception of D.F. 50V 3.0% 6.0% 0603 0.047µF; 0805 0.18µF; 1206 0.47µF 25V 5.0% 10.0% 0805 1µF, 1210 10µF 14.0% 0603 0.33µF 16V 5.0% 10.0% 0402 0.033µF; 0603 0.15µF; 0805 0.68µF; 1206 2.2µF 10V 7.5% 15.0% 0805 2.2µF; 1206 2.2µF, TT series & Cap 1µF 6.3V 15.0% 30.0% 0805 10µF; 1210 100µF Y5V: Rated vol. D.F. Exception of D.F. 50V 7.5% 35V 10.0% 25V 7.5% 10.0% 0603 0.1µF; 0805 0.33µF; 1206 1µF; 1210 4.7µF 12.5% 0402 0.068µF 16V (C<1.0µF) 10.0% 12.5% 0402 0.068µF 16V (C 1.0µF) 12.5% 10V 15.0% 10V		



Appendix I: Reliability Test Conditions and Requirements

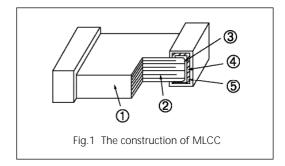
NO.	Item	Test Condition	Requirements			
14.	Humidity Load (Damp Heat)	* Test temp.: 40±2°C * Humidity: 90~95%RH * Test time: 500+24/-0 hrs. * To apply voltage: rated voltage (Max. 500V) * Measurement to be made after keeping at room temp. for 24±2 hrs. (Class I) or 48±4 hrs. (Class II).	* No remarkable damage. * Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger. X7R, X5R: 10V, within ±12.5% 6.3V, with ±25% Y5V: 10V, within ±30% 6.3V, within ±30 to -40% * Q/D.F. value: NP0: Cap 30pF, Q 200; Cap<30pF, Q 100+10/3C			
			X7R, X5R: Rated vol. D.F. Exception of D.F.			
			Rated vol. D.F. Exception of D.F. 50V 7.5%			
15.	* Test temp.: NP0, X7R: 125±3°C X5R, Y5V: 85±3°C * To apply voltage: (1) 6.3V or C 10µF (for X7R, X5R): 150% of rated voltage. (2) 6.3V <v<500v (3)="" (4)="" (class="" (for="" (max.="" *="" -0="" 1000+24="" 120%="" 150%="" 200%="" 24±2="" 3600v)="" 48±4="" 500v:="" 630v:="" after="" and="" at="" be="" c<10µf="" for="" hrs.="" i)="" ii).<="" keeping="" made="" measurement="" of="" or="" rated="" room="" temp.="" test="" th="" time:="" to="" v="" voltage.="" x5r):="" x7r,=""><th>* No remarkable damage. * Cap change: NPO: within ±3.0% or ±0.3pF whichever is larger. X7R, X5R: 10V, within ±12.5% 6.3V, with ±25% Y5V: 10V, within ±30% 6.3V, within ±30 to -40% * Q/D.F. value: NPO: Cap 30pF, Q 350 10pF Cap<30pF, Q 275+2.5C Cap<10pF, Q 200+10C X7R, X5R: Rated vol. D.F. Exception of D.F. 50V 3.0% 6.0% 0603 0.047µF; 0805 0.18µF, 1206 0.47µF 25V 5.0% 10.0% 0805 1µF, 1210 10µF 14.0% 0603 0.33µF 16V 5.0% 10.0% 0805 0.68µF; 1206 2.2µF 10V 7.5% 15.0% 0805 2.2µF; 1206 2.2µF TT series & Cap 1µF</th></v<500v>		* No remarkable damage. * Cap change: NPO: within ±3.0% or ±0.3pF whichever is larger. X7R, X5R: 10V, within ±12.5% 6.3V, with ±25% Y5V: 10V, within ±30% 6.3V, within ±30 to -40% * Q/D.F. value: NPO: Cap 30pF, Q 350 10pF Cap<30pF, Q 275+2.5C Cap<10pF, Q 200+10C X7R, X5R: Rated vol. D.F. Exception of D.F. 50V 3.0% 6.0% 0603 0.047µF; 0805 0.18µF, 1206 0.47µF 25V 5.0% 10.0% 0805 1µF, 1210 10µF 14.0% 0603 0.33µF 16V 5.0% 10.0% 0805 0.68µF; 1206 2.2µF 10V 7.5% 15.0% 0805 2.2µF; 1206 2.2µF TT series & Cap 1µF			
			11 Series & Cap TµF			



Appendix II: General Information

Constructions

No.	Na	me	NPO/X7R	X7R/X5R/Y5V
1	Ceramic	material	BaTiO₃ based	
2	Inner el	ectrode	AgPd alloy	Ni
3		Inner layer	Ag	Cu
4	Termination	Middle layer	Ni	
5		Outer layer	Sn (Matt)	



Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering.
- b. To store products on the shelf and avoid exposure to moisture.
- c. Don't expose products to excessive shock, vibration, direct sunlight and so on.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.

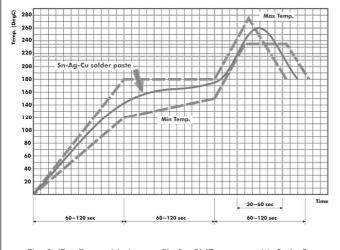


Fig. 2 IR reflow soldering profile for SMT process with SnAgCu series solder paste.

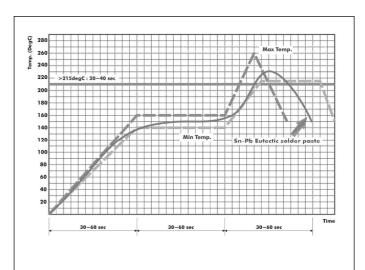


Fig. 3 IR reflow soldering profile for SMT process with eutectic SnPb solder paste.